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1-18-02

PATENT

S/N Unknown

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Paul A. Farrar et al. Examiner: Unknown
Serial No.: Unknown Group Art Unit: Unknown
Filed: Herewith Docket: 303.469US3
Title: THERMAL PROCESSING OF METAL ALLOYS FOR AN IMPROVED CMP
PROCESS IN INTEGRATED CIRCUIT FABRICATION

PRELIMINARY AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

When the above-identified patent application is taken up for consideration, please amend the application as follows:

IN THE SPECIFICATION

On page 1, please add the following new paragraph under the title:

A1 --This application is a Continuation of U.S. Application No. 09/038,252, filed on March
10, 1998. -- *now US 6,316,356* *CASE 81203*

IN THE CLAIMS

Please cancel claims 1-17 after adding the following new claims.

20. A memory device comprising:
an array of memory cells;
internal circuitry; and
metal contacts and interconnects coupled to the memory cells and internal circuitry,
wherein the metal contacts and interconnects are formed by annealing the memory at a
temperature sufficient to drive alloy dopants into solid solution prior to polishing the memory
device to remove portions of a metal layer and form the metal contacts and interconnects.
21. The memory device of claim 20 wherein the memory device is annealed following
polishing of the memory device to increase the conductivity of the metal contacts and
interconnects.